

ABSTRACT OF THE DISCLOSURE

A semiconductor integrated circuit device is provided in which (i) inspection pads are arranged along one side or two opposite sides of the semiconductor integrated circuit device for bonding pads arranged along the sides other than the side or the two opposite sides and (ii) the bonding pads are connected to their respective inspection pads by connection wires. The inspection is carried out by applying probe needles to the pads (inspection pads and bonding pads) arranged only along one side or two opposite sides of the semiconductor integrated circuit device. The invention also provides a semiconductor integrated circuit package with leads on four sides includes a semiconductor integrated circuit device with bonding pads laid along one pair of opposite sides of the four sides, and a table for supporting the semiconductor integrated circuit device. While the bonding pads along the pair of opposite sides of the semiconductor integrated circuit device are connected with leads along the four sides of the package, and some leads are bent toward the respective pads. The present invention the inspection of a plurality of semiconductor integrated circuit devices with probe needles at a time.

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